

#### **Features and Benefits**

- Up to 150 mA constant-current outputs
- Undervoltage lockout
- Low-power CMOS logic and latches
- High data input rate
- Similar to Toshiba TD62715FN
- High/low output current function
- Digital dimming control

### **Packages**

20-pin DIP (A package)



20-pin SOICW (LW package)



Not to scale

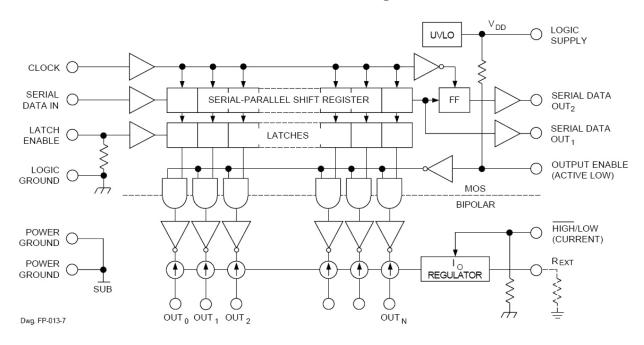
#### Description

The A6277 is specifically designed for LED display applications. Each BiCMOS device includes an 8-bit CMOS shift register, accompanying data latches, and eight NPN constant-current sink drivers. Two package styles and two operating temperature ranges are available.

The CMOS shift register and latches allow direct interfacing with microprocessor-based systems. With a 5 V logic supply, typical serial data-input rates are up to 20 MHz. The LED drive current is determined by the user selection of a single resistor. A CMOS serial data output permits cascade connections in applications requiring additional drive lines. For inter-digit blanking, all output drivers can be disabled with an ENABLE input high. In addition, a HIGH/LOW function enables full selected current with the application of a logic low, or 50% selected current with the application of a logic high.

Two package styles are provided, a through-hole DIP (suffix A), and a surface-mount SOIC (LW). The copper leadframe and low logic-power dissipation allow the DIP to sink 122 mA through all outputs continuously over the operating temperature range (1.0 V drop, 85°C). Both packages are lead (Pb) free, with 100% matte-tin leadframe plating.

#### **Functional Block Diagram**



#### **Selection Guide**

Part Number	Packing	Package
A6277EA-T*	20-pin DIP	18 per tube
A6277ELWTR-T	20-pin SOICW	1000 per reel

<sup>\*</sup>Variant is in production but has been determined to be LAST TIME BUY. This classification indicates that the variant is obsolete and notice has been given. Sale of the variant is currently restricted to existing customer applications. The variant should not be purchased for new design applications because of obsolescence in the near future. Samples are no longer available. Status date change November 2, 2009. Deadline for receipt of LAST TIME BUY orders is April 30, 2010.

#### Absolute Maximum Ratings\*

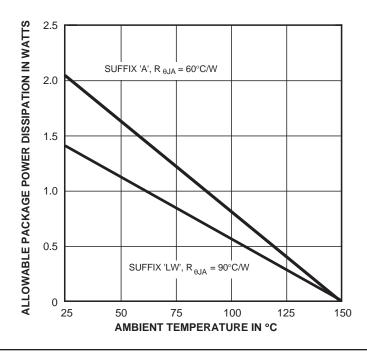
Characteristic	Symbol	Notes	Rating	Units
Supply Voltage	V <sub>DD</sub>		7.0	V
Output Voltage Range	Vo		-0.5 to 24	V
Input Voltage Voltage	V <sub>I</sub>		$-0.4 \text{ to V}_{DD} + 0.4$	V
Output Current	Io		150	mA
Operating Ambient Temperature	T <sub>A</sub>	Range E	-40 to 85	°C
Maximum Junction Temperature	T <sub>J</sub> (max)		150	°C
Storage Temperature	T <sub>stg</sub>		-55 to 150	°C

<sup>\*</sup> Caution: These CMOS devices have input static protection (Class 2) but are still susceptible to damage if exposed to extremely high static electrical charges.

#### Thermal Characteristics may require derating at maximum conditions, see application information

Characteristic	Symbol	Test Conditions*	Value	Units
Package Thermal Resistance	D	Package A, on 1-layer PCB	60	°C/W
Package Thermal Resistance	$R_{ heta JA}$	Package LW, 1-layer PCB	90	°C/W

<sup>\*</sup>Additional thermal information available on the Allegro website.





## ELECTRICAL CHARACTERISTICS at $T_A = +25^{\circ}C$ , $V_{H/L} = V_{DD} = 5$ V (unless otherwise noted).

Characteristic	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Supply Voltage Range	$V_{DD}$	Operating	4.5	5.0	5.5	V
Under-Voltage Lockout	$V_{DD(UV)}$	$V_{DD} = 0 \text{ to } 5 \text{ V}$	3.4	_	4.0	V
Output Current	Io	$V_{CE}$ = 1.0 V, $R_{EXT}$ = 160 $\Omega$	100	120	140	mA
(any single output)		$V_{CE}$ = 0.4 V, $R_{EXT}$ = 470 $\Omega$	34	42	48	mA
Output Current Matching	$\Delta I_{O}$	$0.4 \text{ V} \le V_{CE(A)} = V_{CE(B)} \le 1.0 \text{ V}$ :				
(difference between any		$R_{EXT} = 160 \Omega$	_	±1.5	±6.0	%
two outputs at same V <sub>CE</sub> )		$R_{EXT} = 470 \Omega$	_	±1.5	±6.0	%
Output Leakage Current	I <sub>CEX</sub>	V <sub>OH</sub> = 20 V	_	1.0	5.0	μΑ
Logic Input Voltage	V <sub>IH</sub>		0.7V <sub>DD</sub>	_	_	V
	V <sub>IL</sub>		ı	_	0.3V <sub>DD</sub>	V
SERIAL DATA OUT Voltage	$V_{OL}$	I <sub>OL</sub> = 1.0 mA	ı	_	0.4	٧
(SDO <sub>1</sub> & SDO <sub>2</sub> )	V <sub>OH</sub>	I <sub>OH</sub> = -1.0 mA	4.6	_	_	V
Input Resistance	Rı	ENABLE input, pull up	150	300	600	kΩ
		LATCH & HIGH/LOW inputs, pull down	100	270	400	kΩ
Supply Current	I <sub>DD(OFF)</sub>	$R_{EXT}$ = open, $V_{OE}$ = 5 V	_	0.8	1.6	mA
		$R_{EXT} = 470 \Omega$ , $V_{OE} = 5 V$	3.5	6.5	9.5	mA
		$R_{EXT} = 160 \Omega$ , $V_{OE} = 5 V$	14	17	22	mA
	I <sub>DD(ON)</sub>	$R_{EXT} = 470 \Omega$ , $V_{OE} = 0 V$	5.0	10	15	mA
		$R_{EXT} = 160 \Omega$ , $V_{OE} = 0 V$	20	27	40	mA

Typical Data is at  $V_{DD} = 5 \text{ V}$  and is for design information only.



SWITCHING CHARACTERISTICS at T<sub>A</sub> = 25°C, V<sub>DD</sub> = V<sub>IH</sub> = 5 V, V<sub>CE</sub> = 0.4 V, V<sub>IL</sub> = 0 V, R<sub>EXT</sub> = 470  $\Omega$ , I<sub>O</sub> = 40 mA, V<sub>L</sub> = 3 V, R<sub>L</sub> = 65  $\Omega$ , C<sub>L</sub> = 10.5 pF.

				Li	imits	
Characteristic	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Propagation Delay Time	t <sub>pHL</sub>	CLOCK-OUT <sub>n</sub>	_	350	1000	ns
		LATCH-OUT <sub>n</sub>	_	350	1000	ns
		ENABLE-OUT <sub>n</sub>	_	350	1000	ns
		CLOCK-SERIAL DATA OUT₁	_	40	_	ns
Propagation Delay Time	t <sub>pLH</sub>	CLOCK-OUT <sub>n</sub>	_	300	1000	ns
		LATCH-OUT <sub>n</sub>	_	400	1000	ns
		ENABLE-OUT <sub>n</sub>	_	380	1000	ns
		CLOCK-SERIAL DATA OUT <sub>2</sub>	_	40	_	ns
Output Fall Time	t <sub>f</sub>	90% to 10% voltage	150	250	1000	ns
Output Rise Time	t <sub>r</sub>	10% to 90% voltage	150	250	600	ns

#### RECOMMENDED OPERATING CONDITIONS

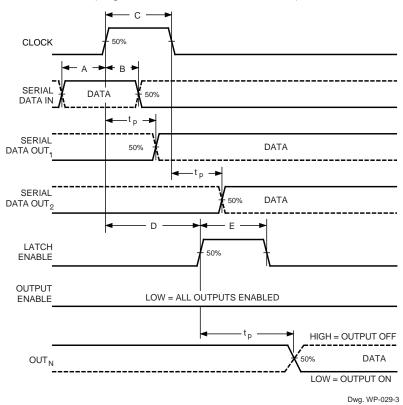
Characteristic	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply Voltage	$V_{DD}$		4.5	5.0	5.5	<b>V</b>
Output Voltage	Vo		_	1.0	4.0	>
Output Current	Io	Continuous, any one output	_	_	150	mA
	I <sub>OH</sub>	SERIAL DATA OUT	_	_	-1.0	mA
	I <sub>OL</sub>	SERIAL DATA OUT	_	_	1.0	mA
Logic Input Voltage	V <sub>IH</sub>		0.7V <sub>DD</sub>	_	-	V
	V <sub>IL</sub>		_	_	0.3V <sub>DD</sub>	V
Clock Frequency	f <sub>CK</sub>	Cascade operation	_	_	10	MHz

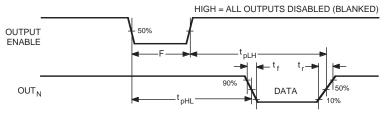


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#### TIMING REQUIREMENTS and SPECIFICATIONS

(Logic Levels are V<sub>DD</sub> and Ground)





Dwg. WP-030-1A

A. Data Active Time Before Clock Fulse	
(Data Set-Up Time), t <sub>su(D)</sub>	60 ns
<b>B.</b> Data Active Time After Clock Pulse	
(Data Hold Time), t <sub>h(D)</sub>	20 ns
C. Clock Pulse Width, t <sub>w(CK)</sub>	50 ns
<b>D.</b> Time Between Clock Activation	
and Latch Enable, t <sub>su(L)</sub>	100 ns
<b>E.</b> Latch Enable Pulse Width, t <sub>w(L)</sub>	100 ns
<b>F.</b> Output Enable Pulse Width, t <sub>w(OE)</sub>	<b>4.5</b> µs
NOTE – Timing is representative of a 10 MHz clock.	
Significantly higher speeds are attainable.	
— Max. Clock Transition Time, $t_r$ or $t_f$	10 µs

A Data Active Time Refore Clock Pulse

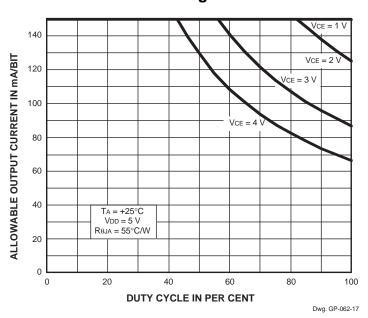
Information present at any register is transferred to the respective latch when the LATCH ENABLE is high (serial-to-parallel conversion). The latches will continue to accept new data as long as the LATCH ENABLE is held high. Applications where the latches are bypassed (LATCH ENABLE tied high) will require that the OUTPUT ENABLE input be high during serial data entry.

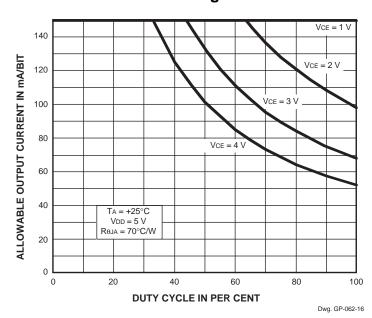
When the OUTPUT ENABLE input is high, the output source drivers are disabled (OFF). The information stored in the latches is not affected by the OUTPUT ENABLE input. With the OUTPUT ENABLE input low, the outputs are controlled by the state of their respective latches.

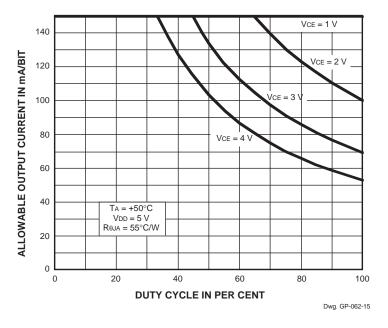


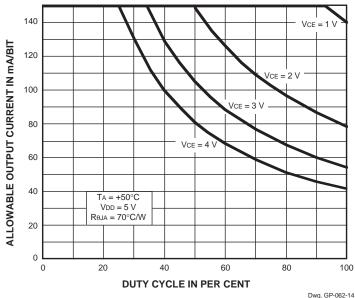
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# ALLOWABLE OUTPUT CURRENT AS A FUNCTION OF DUTY CYCLE Package A Package LW

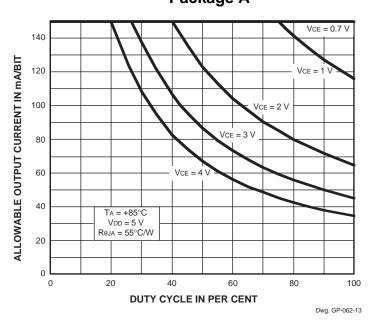


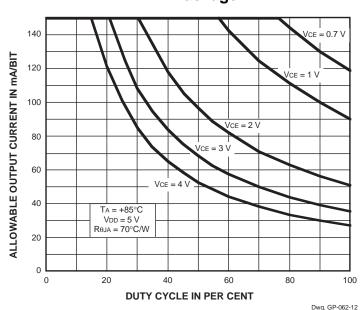




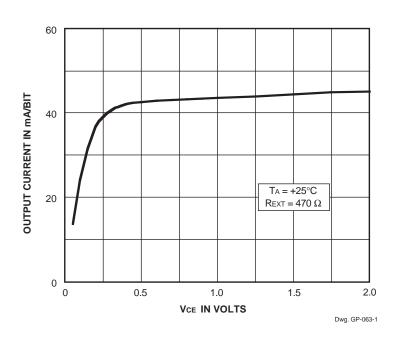


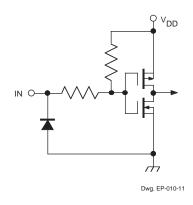
#### **ALLOWABLE OUTPUT CURRENT AS A FUNCTION OF DUTY CYCLE (cont.)** Package A Package LW



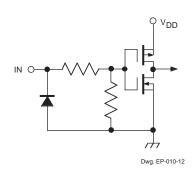


#### TYPICAL CHARACTERISTICS

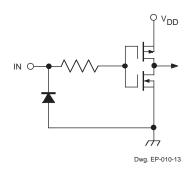




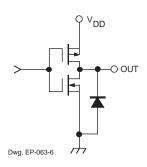
**OUTPUT ENABLE** (active low)



LATCH ENABLE and HIGH/LOW



**CLOCK and SERIAL DATA IN** 



**SERIAL DATA OUT** 

#### **TRUTH TABLE**

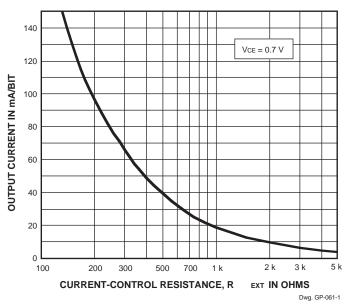
Serial			nift F	Regi	ster	Conte	ents	Serial	Latch		Lat	ch C	onte	ents		Output		0	utpu	ıt Co	onten	ts
Data Input	Clock		l <sub>2</sub>	I <sub>3</sub>		I <sub>N-1</sub>	I <sub>N</sub>	Data Output	Data Enable Output Input	I <sub>1</sub>	l <sub>2</sub>	I <sub>3</sub>		I <sub>N-1</sub>	I <sub>N</sub>	Enable Input	I <sub>1</sub>	l <sub>2</sub>	I <sub>3</sub>		I <sub>N-1</sub>	I <sub>N</sub>
Н	7	Н	R <sub>1</sub>	R <sub>2</sub>		R <sub>N-2</sub>	R <sub>N-1</sub>	R <sub>N-1</sub>														
L	۲	L	R <sub>1</sub>	$R_2$		R <sub>N-2</sub>	R <sub>N-1</sub>	R <sub>N-1</sub>														
Х	l	R <sub>1</sub>	$R_2$	$R_3$		R <sub>N-1</sub>	$R_N$	R <sub>N</sub>														
		Χ	Χ	Χ		Χ	Χ	X	L	R <sub>1</sub>	$R_2$	$R_3$		R <sub>N-1</sub>	R <sub>N</sub>							
		P <sub>1</sub>	P <sub>2</sub>	P <sub>3</sub>		P <sub>N-1</sub>	PN	P <sub>N</sub>	Н	P <sub>1</sub>	P <sub>2</sub>	P <sub>3</sub>		P <sub>N-1</sub>	P <sub>N</sub>	L	P <sub>1</sub>	P	2 P <sub>3</sub>		P <sub>N-1</sub>	P <sub>N</sub>
										Х	Χ	Χ		Χ	Χ	Н	Н	Н	Н		Н	Н

L = Low Logic (Voltage) Level H = High Logic (Voltage) Level X = Irrelevant P = Present State R = Previous State



#### **Applications Information**

The load current per bit  $(I_O)$  is set by the external resistor  $(R_{EXT})$  as shown in the figure below.



Package Power Dissipation  $(P_D)$ . The maximum allowable package power dissipation is determined as

$$P_{D}(max) = (150 - T_{A})/R_{\theta JA}.$$

The actual package power dissipation is

$$P_{D}(act) = dc(V_{CE} \bullet I_{O} \bullet 8) + (V_{DD} \bullet I_{DD}).$$

When the load supply voltage is greater than 3 V to 5 V, considering the package power dissipating limits of these devices, or if  $P_D(act) > P_D(max)$ , an external voltage reducer ( $V_{DROP}$ ) should be used.

**Load Supply Voltage (V**<sub>LED</sub>). These devices are designed to operate with driver voltage drops (V<sub>CE</sub>) of 0.4 V to 0.7 V with LED forward voltages (V<sub>F</sub>) of 1.2 V to 4.0 V. If higher voltages are dropped across the driver, package power dissipation will be increased significantly. To minimize package power dissipation, it is recommended to use the lowest possible load supply voltage or to set any series dropping voltage (V<sub>DROP</sub>) as

$$V_{DROP} = V_{LED}$$
 -  $V_F$  -  $V_{CE}$ 

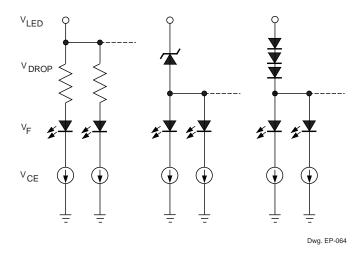
with  $V_{DROP} = I_o \bullet R_{DROP}$  for a single driver, or a Zener diode  $(V_Z)$ , or a series string of diodes (approximately

0.7 V per diode) for a group of drivers. If the available voltage source will cause unacceptable dissipation and series resistors or diode(s) are undesirable, a regulator such as the Sanken Series SAI or Series SI can be used to provide supply voltages as low as 3.3 V.

For reference, typical LED forward voltages are:

White	3.5 - 4.0  V
Blue	3.0 - 4.0  V
Green	1.8 - 2.2  V
Yellow	2.0 - 2.1  V
Amber	1.9 – 2.65 V
Red	1.6 – 2.25 V
Infrared	1.2 - 1.5  V

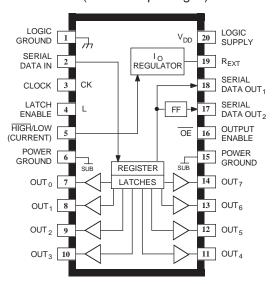
**Pattern Layout.** This device has separate logic-ground and power-ground terminals. If ground pattern layout contains large common-mode resistance, and the voltage between the system ground and the LATCH ENABLE or CLOCK terminals exceeds 2.5 V (because of switching noise), these devices may not operate correctly.



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## **Pin-out Diagram**

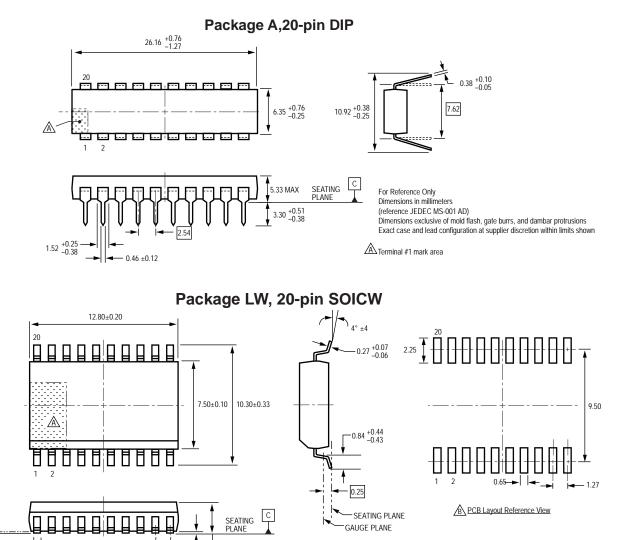
(A and LW packages)



#### **TERMINAL DESCRIPTION**

Terminal No.	Terminal Name	Function
1	LOGIC GROUND	Reference terminal for control logic.
2	SERIAL DATA IN	Serial-data input to the shift-register.
3	CLOCK	Clock input terminal for data shift on rising edge.
4	LATCH ENABLE	Data strobe input terminal; serial data is latched with high-level input.
5	HIGH/LOW (CURRENT)	Logic low for 100% of programmed current level; logic high for 50% of programmed current level.
6	POWER GROUND	Ground.
7-14	$\mathrm{OUT}_{0-7}$	The eight current-sinking output terminals.
15	POWER GROUND	Ground.
16	OUTPUT ENABLE	When (active) low, the output drivers are enabled; when high, all output drivers are turned OFF (blanked).
17	SERIAL OUT <sub>2</sub>	CMOS serial-data output (on clock falling edge).
18	SERIAL OUT <sub>1</sub>	CMOS serial-data output (on clock rising edge) to the following shift-registers.
19	$R_{\mathrm{EXT}}$	An external resistor at this terminal establishes the output current for all sink drivers.
20	LOGIC SUPPLY	$(V_{\rm DD})$ The logic supply voltage. Typically 5 V.





A Terminal #1 mark area

Reference pad layout (reference IPC SOIC127P1030X265-20M)

All pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary

to meet application process requirements and PCB layout tolerances

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For Reference Only Dimensions in millimeters

(Reference JEDEC MS-013 AC)

○ 0.10 C

0.41 ±0.10

The products described here are manufactured under one or more U.S. patents or U.S. patents pending.

Dimensions exclusive of mold flash, gate burrs, and dambar protrusions

Exact case and lead configuration at supplier discretion within limits shown

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2.65 MAX 0.20 ±0.10

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